



**THE DATASHEET OF
FQD5P10TM**





ON Semiconductor®

FQD5P10

P-Channel QFET[®] MOSFET

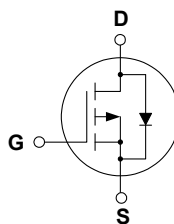
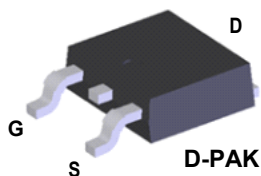
-100 V, -3.6 A, 1.05Ω

Description

This P-Channel enhancement mode power MOSFET is produced using ON Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, DC motor control, and variable switching power applications.

Features

- -3.6 A, -100 V, $R_{DS(on)} = 1.05 \Omega$ (Max.) @ $V_{GS} = -10$ V, $I_D = 1.8$ A
- Low Gate Charge (Typ. 6.3 nC)
- Low Crss (Typ. 18 pF)
- 100% avalanche tested



Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter	FQD5P10	Unit
V _{DSS}	Drain-Source Voltage	-100	V
I _D	Drain Current	- Continuous (T _C = 25°C)	-3.6
		- Continuous (T _C = 100°C)	-2.28
I _{DM}	Drain Current	- Pulsed (Note 1)	-14.4
V _{GSS}	Gate-Source Voltage	± 30	V
E _{AS}	Single Pulsed Avalanche Energy (Note 2)	55	mJ
I _{AR}	Avalanche Current (Note 1)	-3.6	A
E _{AR}	Repetitive Avalanche Energy (Note 1)	2.5	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	-6.0	V/ns
P _D	Power Dissipation (T _A = 25°C) *	2.5	W
	Power Dissipation (T _C = 25°C)	25	W
	- Derate above 25°C	0.2	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to +150	°C
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	°C

Thermal Characteristics

Symbol	Parameter	FQD5P10	Unit
R _{θJC}	Thermal Resistance, Junction-to-Case, Max.	5.0	°C/W
R _{θJA}	Thermal Resistance, Junction-to-Ambient *	50	°C/W
R _{θJA}	Thermal Resistance, Junction-to-Ambient, Max.	110	°C/W

* When mounted on the minimum pad size recommended (PCB Mount)

Electrical Characteristics

$T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit	
Off Characteristics							
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = -250\ \mu\text{A}$	-100	--	--	V	
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = -250\ \mu\text{A}$, Referenced to 25°C	--	-0.1	--	V/ $^\circ\text{C}$	
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -100\text{ V}, V_{GS} = 0\text{ V}$	--	--	-1	μA	
		$V_{DS} = -80\text{ V}, T_C = 125^\circ\text{C}$	--	--	-10	μA	
I_{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = -30\text{ V}, V_{DS} = 0\text{ V}$	--	--	-100	nA	
I_{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = 30\text{ V}, V_{DS} = 0\text{ V}$	--	--	100	nA	
On Characteristics							
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\ \mu\text{A}$	-2.0	--	-4.0	V	
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = -10\text{ V}, I_D = -1.8\text{ A}$	--	0.82	1.05	Ω	
g_{FS}	Forward Transconductance	$V_{DS} = -40\text{ V}, I_D = -1.8\text{ A}$	--	2.3	--	S	
Dynamic Characteristics							
C_{iss}	Input Capacitance	$V_{DS} = -25\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$	--	190	250	pF	
C_{oss}	Output Capacitance		--	70	90	pF	
C_{rss}	Reverse Transfer Capacitance		--	18	25	pF	
Switching Characteristics							
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = -50\text{ V}, I_D = -4.5\text{ A},$ $R_G = 25\ \Omega$	--	9	30	ns	
t_r	Turn-On Rise Time		--	70	150	ns	
$t_{d(off)}$	Turn-Off Delay Time		(Note 4)	--	12	35	ns
t_f	Turn-Off Fall Time		(Note 4)	--	30	70	ns
Q_g	Total Gate Charge	$V_{DS} = -80\text{ V}, I_D = -4.5\text{ A},$ $V_{GS} = -10\text{ V}$	--	6.3	8.2	nC	
Q_{gs}	Gate-Source Charge		(Note 4)	--	1.7	--	nC
Q_{gd}	Gate-Drain Charge		(Note 4)	--	3.0	--	nC
Drain-Source Diode Characteristics and Maximum Ratings							
I_S	Maximum Continuous Drain-Source Diode Forward Current		--	--	-3.6	A	
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	-14.4	A	
V_{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = -3.6\text{ A}$	--	--	-4.0	V	
t_{rr}	Reverse Recovery Time	$V_{GS} = 0\text{ V}, I_S = -4.5\text{ A},$ $di_F / dt = 100\text{ A}/\mu\text{s}$	--	85	--	ns	
Q_{rr}	Reverse Recovery Charge		--	0.27	--	μC	

Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. $L = 6.4\text{ mH}, I_{AS} = -3.6\text{ A}, V_{DD} = -25\text{ V}, R_G = 25\ \Omega$, Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} \leq -4.5\text{ A}, di/dt \leq 300\text{ A}/\mu\text{s}, V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$
4. Essentially independent of operating temperature

Typical Characteristics

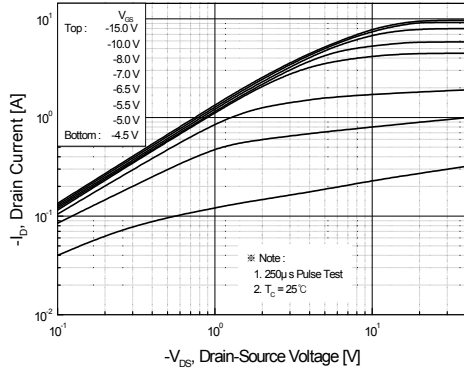


Figure 1. On-Region Characteristics

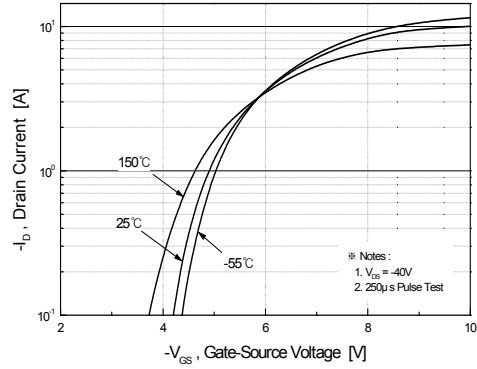


Figure 2. Transfer Characteristics

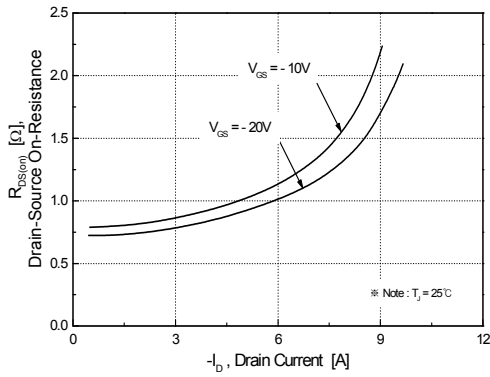


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

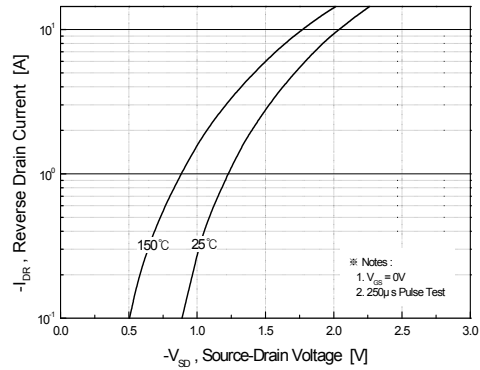


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

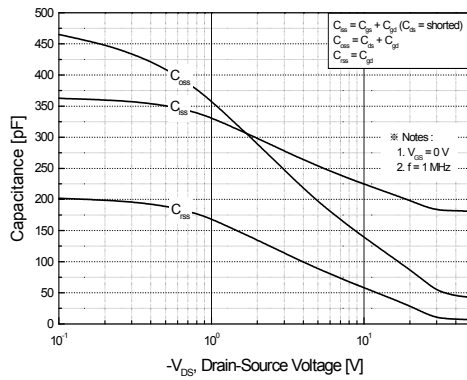


Figure 5. Capacitance Characteristics

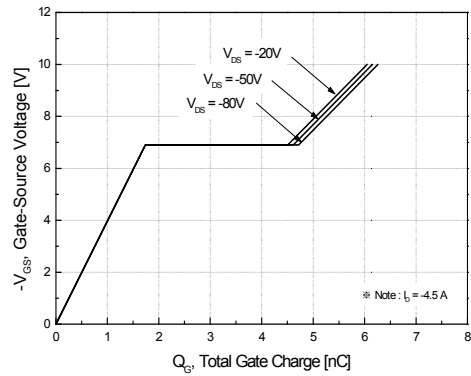


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

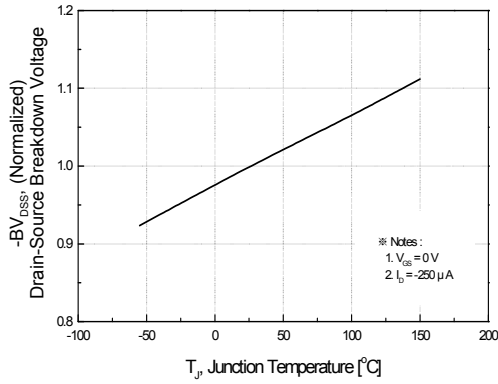


Figure 7. Breakdown Voltage Variation vs. Temperature

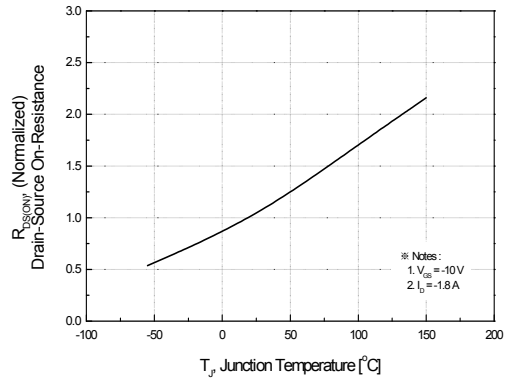


Figure 8. On-Resistance Variation vs. Temperature

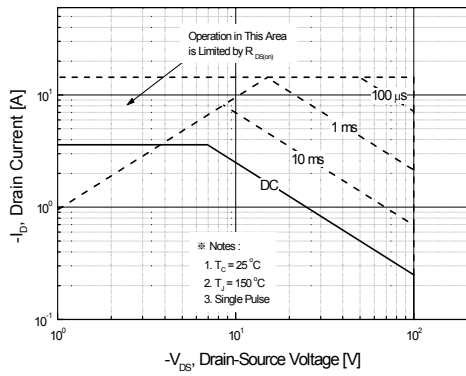


Figure 9. Maximum Safe Operating Area

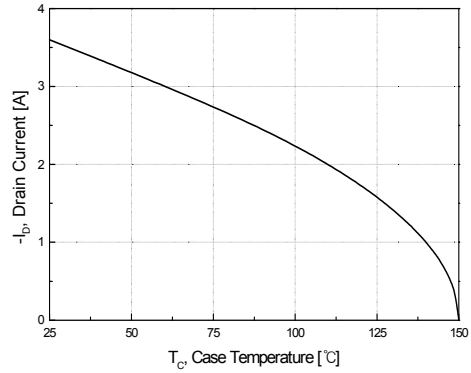


Figure 10. Maximum Drain Current vs. Case Temperature

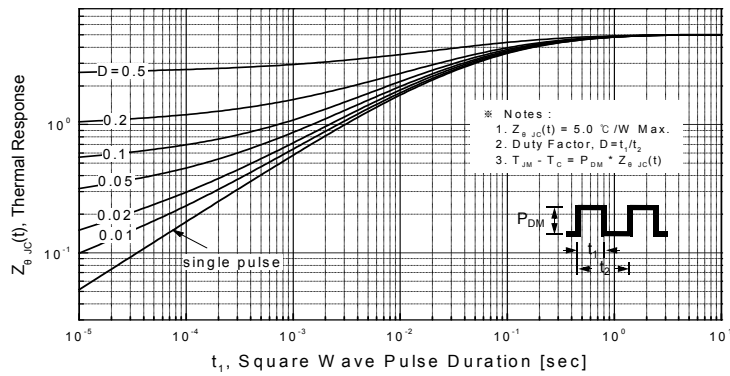
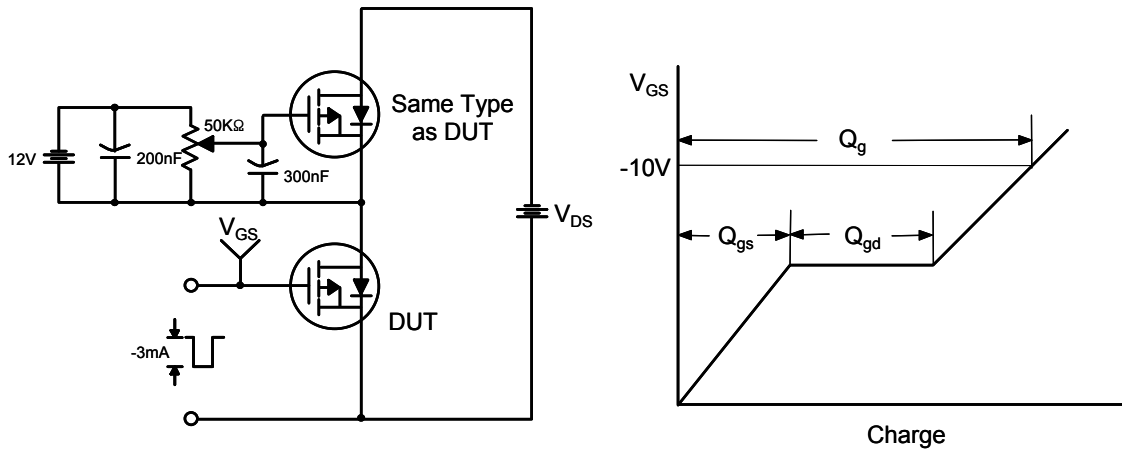
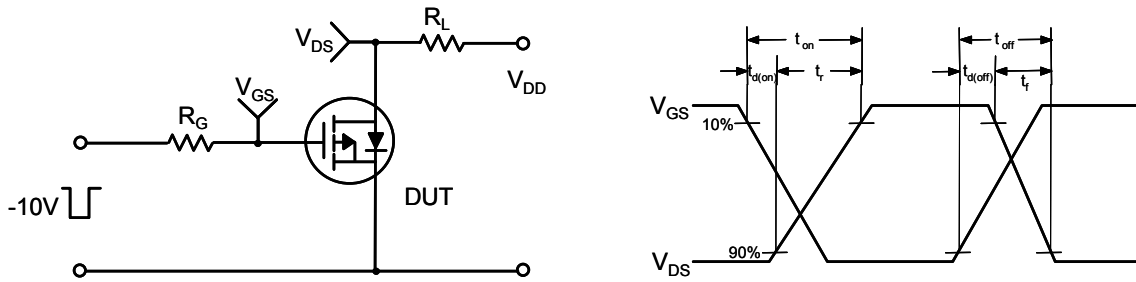


Figure 11. Transient Thermal Response Curve

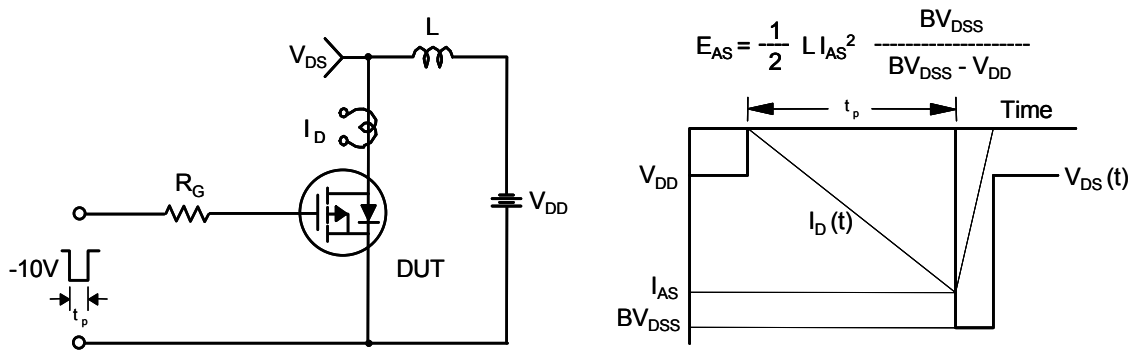
Gate Charge Test Circuit & Waveform



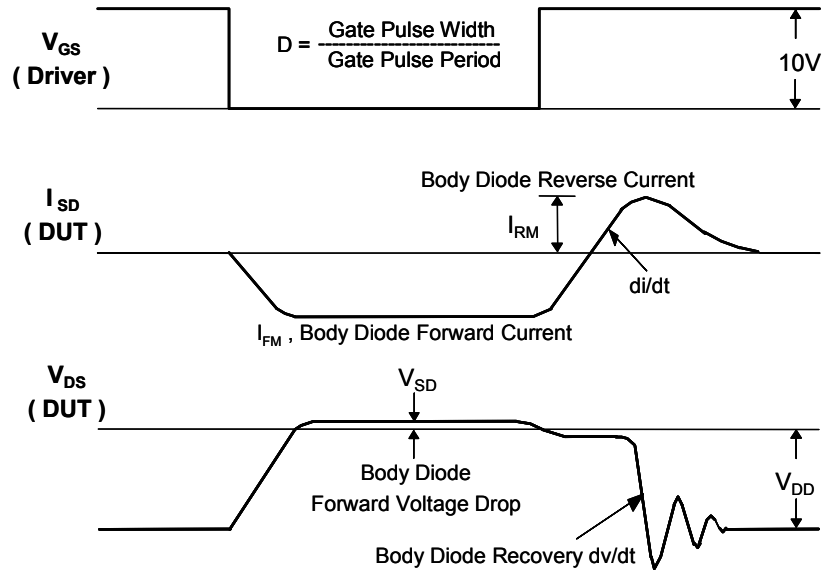
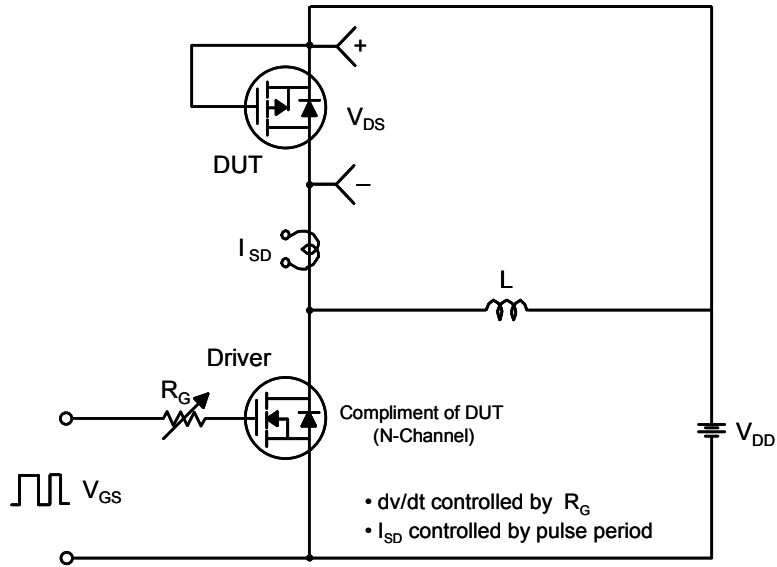
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms

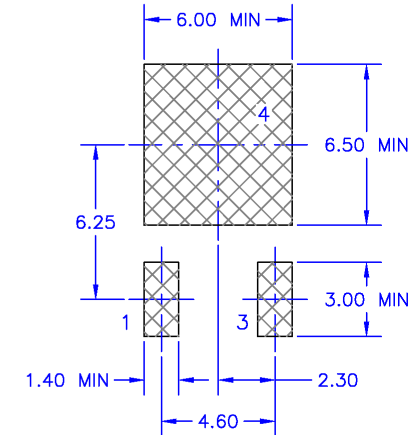
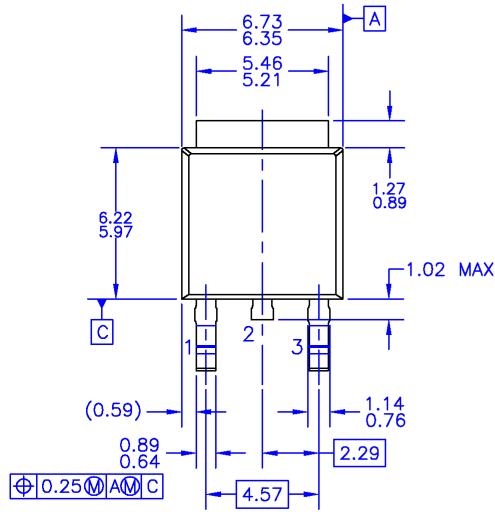


Peak Diode Recovery dv/dt Test Circuit & Waveforms

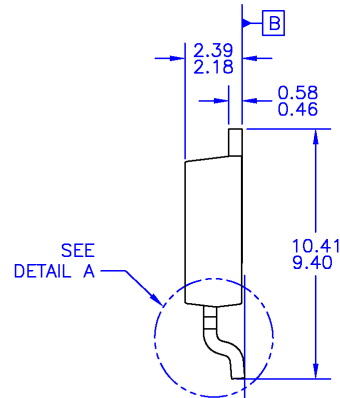
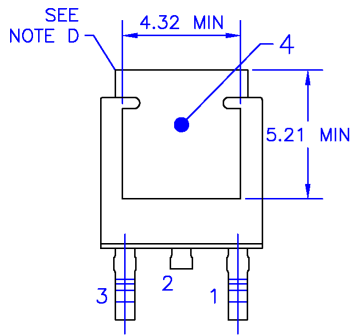


Package Dimensions

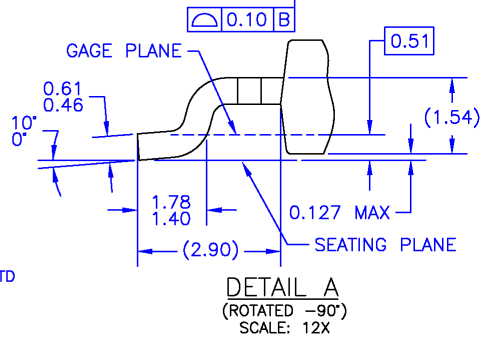
D-PAK



LAND PATTERN RECOMMENDATION



- NOTES: UNLESS OTHERWISE SPECIFIED
- A) THIS PACKAGE CONFORMS TO JEDEC, TO-252, ISSUE C, VARIATION AA.
 - B) ALL DIMENSIONS ARE IN MILLIMETERS.
 - C) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
 - D) HEAT SINK TOP EDGE COULD BE IN CHAMFERED CORNERS OR EDGE PROTRUSION.
 - E) PRESENCE OF TRIMMED CENTER LEAD IS OPTIONAL.
 - F) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.
 - G) LAND PATTERN RECOMMENDATION IS BASED ON IPC7351A STD TO220P1003X238-3N.
 - H) DRAWING NUMBER AND REVISION: MKT-T0252A03REV8



Dimensions in Millimeters

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